
HB526R464DBK Series

1,048,576-word $\times$ 64-bit $\times$ 4-bank Synchronous Dynamic RAM
Module

HITACHI

Description

The HB526R464DBK is a 1M $\times$ 64 $\times$ 4 banks Synchronous Dynamic RAM Small Outline Dual In-line Memory Module (S.O.DIMM), mounted 8 pieces of 16-Mbit SDRAM (HM5216805TB) sealed in TCP package and 1 piece of serial EEPROM (24C02) for Presence Detect (PD). An outline of the HB526R464DBK is 144-pin Zig Zag Dual tabs socket type compact and thin package. Therefore, the HB526R464DBK makes high density mounting possible without surface mount technology. The HB526R464DBK provides common data inputs and outputs. Decoupling capacitors are mounted beside each TCP on the module board.

Features

- 144-pin Zig Zag Dual tabs socket type
 - Outline: 67.60 mm (Length) $\times$ 25.40 mm (Height) $\times$ 3.80 mm (Thickness)
 - Lead pitch : 1.27 mm
- 3.3V (± 0.3 V) power supply
- Clock frequency : 100 MHz / 83 MHz
- LVTTTL interface
- 4 Banks can operates simultaneously and independently
- Burst read/write operation and burst read/single write operation capability
- Programmable burst length : 1/2/4/8/full page
- Programmable burst sequence
 - Sequential/interleave
- Full page burst length capability
 - Sequential burst
 - Burst stop capability
- Programmable $\overline{\text{CAS}}$ latency : 2/3
- 4096 refresh cycles: 64 ms

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- 2 variations of refresh
 - Auto refresh
 - Self refresh

Ordering Information

Type No.	Frequency	Package	Contact pad
HB526R464DBK-10	100 MHz	Small outline DIMM (144-pin)	Gold
HB526R464DBK-12	83 MHz		

Note: The specification of this device is subject to change without notice. Please contact your nearest Hitachi’s Sales Dept. regarding specification.

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